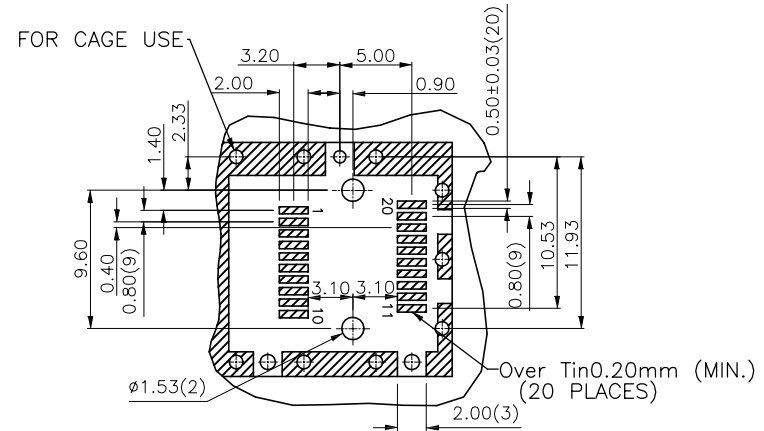
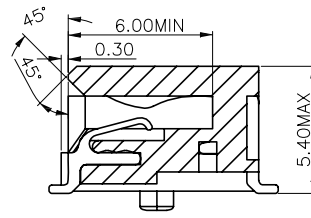
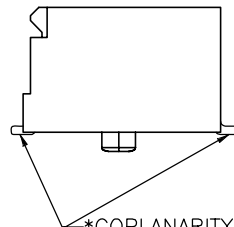
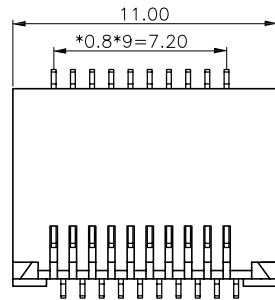


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD



PCB LAYOUT (CONNECTOR) / TOP VIEW

NOTE:
MECHANICAL:

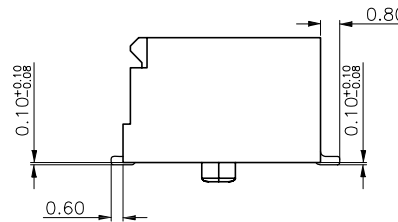
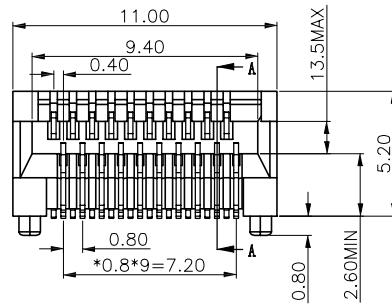
- CONNECTOR MATERIAL:
 1.HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0.
 2.CONTACT: PHOSPHOR BRONZE THICKNESS=0.20mm.
 3.PLATING: GOLD PLATING OVER NICKEL
 4.DURABILITY:250 CYCLES MIN.

ELECTRICAL:

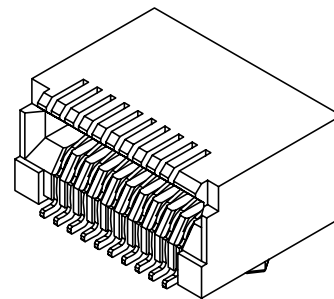
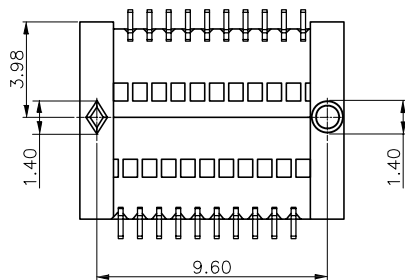
- 1.VOLTAGE RATING : 30 VAC RMS MAX.
 2.CURRENT RATING : 0.5 AMP MAX.
 3.DIFFERENTIAL IMPEDANCE : 100 Ohms.
 4.CAPACITANCE:1.2pF MAX.
 5.CONTACT RESISTANCE: 20 MILLIOHMS MAX.
 6.INSULATION RESISTANCE: 500 MEGAOHMS MIN.
 7.TEMPERATURE:
 SOLDER TEMPERATURE SUGGEST 250°C~270°C.(5 - 10 sec)
 OPERATING:-40°C to +85°C
 STORAGE:-40°C to +85°C

PART NUMBER : SFP-008X-L

GOLD PLATED:
 1- 3u' 2- 6u' 3-15u'
 4-30u' 5-50u'



SECTION A-A



MM (INCH)		DRFT: JON	DATE: 08/15/06	Xmultiple Technologies, Inc.	
TOLERANCES EXCEPT AS NOTED		CHKD	DATE		
		MFO	DATE	TITLE	
		APPVL	DATE	SFP CONNECTOR 20PIN	
		MATERIAL :		DRAWING NO. SFP-008	
		FINISH:		/PART NO. SEE NOTE	
		SCALE :		SIZE: A3	REV: 0
THIRD ANGLE PROJECTION				DO NOT SCALE DRAWING	SHEET X OF Y